

# HAT1110R

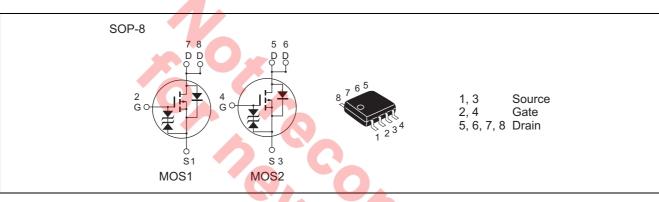
Silicon P Channel Power MOS FET Power Switching

> REJ03G0416-0200 Rev.2.00 Oct.07.2004

# Features

- Capable of –4.5 V gate drive
- Low drive current
- High density mounting

# Outline



# **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	-80	V
Gate to source voltage	V <sub>GSS</sub>	±20	V
Drain current	I <sub>D</sub>	-1	A
Drain peak current	Note1 I <sub>D(pulse)</sub>	-6	A
Reverse drain current	I <sub>DR</sub>	-1	A
Channel dissipation	Pch <sup>Note2</sup>	1.2	W
Channel dissipation	Pch <sup>Note3</sup>	1.8	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. 1 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s

3. 2 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s



# **Electrical Characteristics**

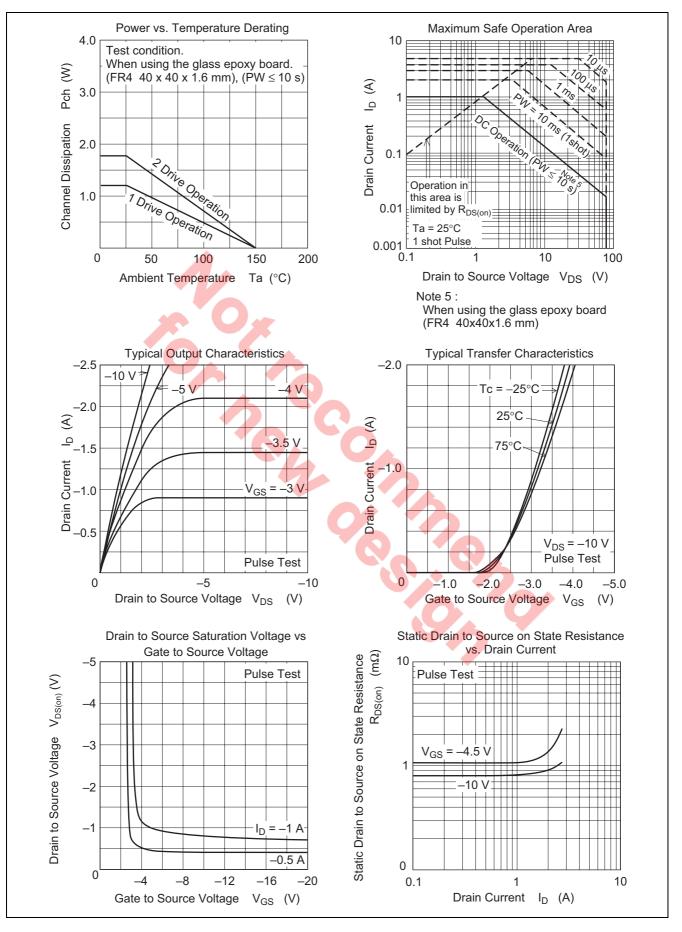
(Ta =	25°C)
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ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	-80	—	—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	±20	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>		—	±10	μΑ	$V_{GS} = \pm 16 V, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>		—	-1	μΑ	$V_{DS} = -80 V, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS(off)</sub>	-1.0	—	-2.5	V	$V_{DS} = -10 V$ , $I_{D} = -1mA$
Static drain to source on state	R <sub>DS(on)</sub>		0.8	1.05	Ω	$I_D = -0.5 \text{ A}, V_{GS} = -10 \text{ V}^{Note4}$
resistance	R <sub>DS(on)</sub>		1.02	1.38	Ω	$I_D = -0.5 \text{ A}, V_{GS} = -4.5 \text{ V}^{Note4}$
Forward transfer admittance	y <sub>fs</sub>	0.4	0.8	—	S	$I_D = -0.5 \text{ A}, V_{DS} = -10 \text{ V}^{Note4}$
Input capacitance	Ciss		170	—	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss		24	—	pF	V <sub>GS</sub> = 0 f = 1MHz
Reverse transfer capacitance	Crss		16	—	pF	
Total gate charge	Qg		3.6	—	nC	V <sub>DD</sub> = -25 V
Gate to source charge	Qgs		0.3	—	nC	V <sub>GS</sub> = -10 V
Gate to drain charge	Qgd		0.7	—	nC	I <sub>D</sub> = -1.0 A
Turn-on delay time	t <sub>d(on)</sub>		14	—	ns	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$
Rise time	tr		12	—	ns	$V_{DD} \approx -30 \text{ V}$
Turn-off delay time	t <sub>d(off)</sub>	_	25	_	ns	$R_L = 60 \Omega$
Fall time	tf		5.5	—	ns	$R_g = 4.7 \Omega$
Body–drain diode forward voltage	V <sub>DF</sub>		-0.86	-1.12	V	$IF = -1.0 A, V_{GS} = 0^{Note4}$
Body–drain diode reverse 🥢	t <sub>rr</sub>		21	_	ns	$IF = -1.0 A, V_{GS} = 0$
recovery time						diF/ dt = 100 A/µs

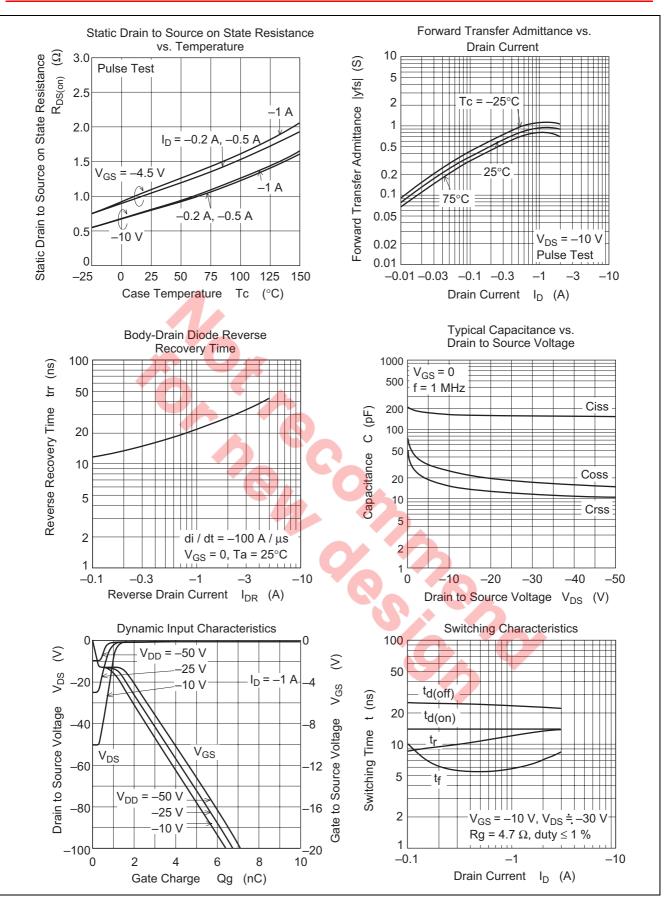
Notes: 4. Pulse test



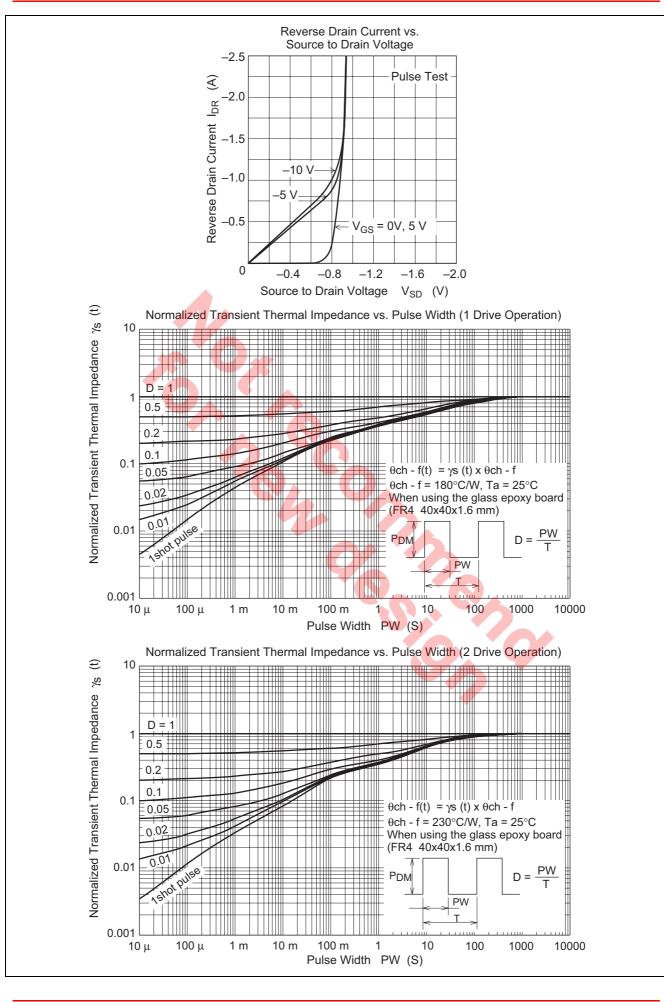
# **Main Characteristics**



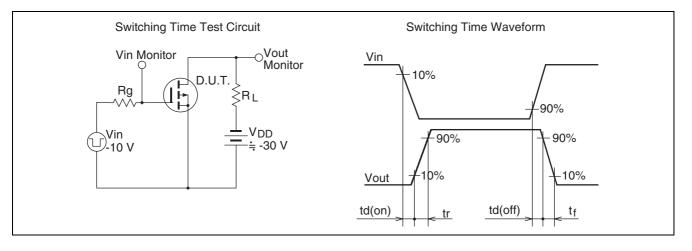




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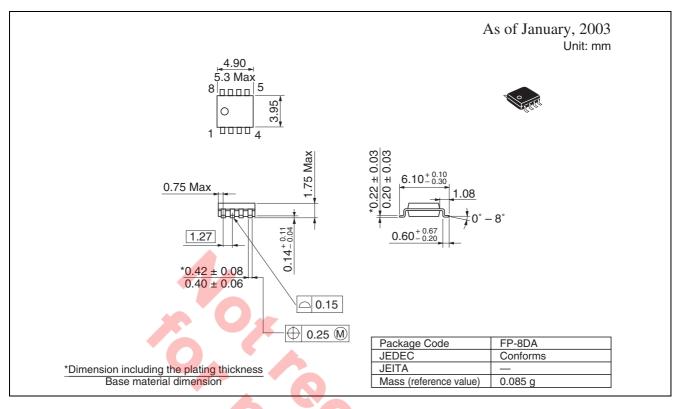








# **Package Dimensions**



# **Ordering Information**

Part Name	Quantity		Shipping Container
HAT1110R-EL-E	2500 pcs	Taping	

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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